



ISSM2022 – International Symposium on Semiconductor Manufacturing
SPONSORSHIP
December 12-13, 2022, Tokyo, Japan

Shozo Saito
Chairman, ISSM2022 Organizing Committee
Device & System Platform Development Center Co., Ltd.
Shuichi Inoue
Vice Chairman, ISSM2022 Organizing Committee
ATONARP INC.
Ayako Shimazaki
Chairman, ISSM2022 Executive Committee
Toshiba Nanoanalysis Corporation

It is our great pleasure to announce that the 29th annual International Symposium on Semiconductor Manufacturing (ISSM) 2022 will be held on December 12-13, 2022 at KFC Hall, Ryogoku, Tokyo in cooperation with e-Manufacturing & Design Collaboration Symposium (eMDC) which is sponsored by TSIA with support from SEMI.

The program will feature keynote speeches by world leading speakers, timely and highlighted topics and networking sessions focusing on equipment/materials/software/services with suppliers' exhibits. ISSM continues to contribute to the growth of the semiconductor industry through its infrastructure for networking, discussion, and information sharing among the world's professionals.

We would like you to cooperate with us by supporting the ISSM 2022.

Please see the benefit of ISSM2022 sponsorship.

Conference Overview

Date: December 12-13, 2022

Location: KFC (Kokusai Fashion Center) Hall
1-6-1 Yokoami Sumidaku,
Tokyo 130-0015 Japan
+81-3-5610-5810

Co-Sponsored by: IEEE Electron Devices Society
Minimal Fab
Semiconductor Equipment Association of Japan (SEAJ)
Semiconductor Equipment and Materials International (SEMI)
Taiwan Semiconductor Industry Association (TSIA)

Endorsement by: The Japan Society of Applied Physics

Area of Interest:

Fab Management

- * Factory Design (FD)
- * Material Handling Management (MH)
- * Manufacturing Strategy (MS)
- * Fab Operation Method (FO)
- * Environment, Safety and Health, Carbon Neutral (ES)
- * Worker and WIP Control (WC)
- * Intelligent Data Management (ID)

Material Technology

- * New Gas, New Liquid, and New Resist Technologies (NM)
- * Material Informatics (MI)
- * New Parts Technology for Process Equipment (NP)

Process Integration

- * Process/Material Optimization (PO)
- * Process Monitoring & Control Method (PM)
- * Yield & Defect Control (YD)
- * Ultraclean Technology (UT)
- * New Process/Metrology Equipment (PE)
- * Manufacturing Technology for Variety Devices (VD)

Final Manufacturing & Packaging

- * Heterogeneous Integration and Packaging (HI)
- * Improvement of Conventional Final Manufacturing Technology (FM)
- * Signal and Power Integrity (SI)



About ISSM

Semiconductor manufacturing technology is reliant on the sum of the total of engineers' experiences and the accumulation of know-how and IP. The complexity of the field prevents a shift to the systematization and universalization of technologies. In order to bring breakthroughs in semiconductor manufacturing to reflect changing and challenging new requirements, the International Symposium on Semiconductor Manufacturing (ISSM) was launched in 1992.

ISSM is an annual conference of semiconductor manufacturing professionals dedicated to sharing technical solutions and opinions on the advancement of manufacturing science, technologies, and management disciplines. ISSM aims to establish new concepts for semiconductor manufacturing technologies and to promote them as systemized and universalized technologies. ISSM's role has been to challenge the concept of shifting from "know-how" to "science" in semiconductor manufacturing technologies. The past symposia have helped to shape the course of development of "manufacturing science," as well as to create new manufacturing technologies.

The Symposium is held under the joint sponsorship of the IEEE Electron Devices Society, Minimal Fab, Semiconductor Equipment and Materials International (SEMI), and Taiwan Semiconductor Industry Association (TSIA). ISSM, with its global range, continuously pushes technological development in order to promote the discovery and utilization of innovative technologies.

ISSM's mission is to achieve the continued prosperity of the semiconductor industry by bringing about breakthroughs in semiconductor manufacturing technologies through networking between engineers in research and development fields and their counterparts in the manufacturing field.



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Sponsorship of ISSM2022 in Tokyo, Japan

	Platinum Sponsor	Gold Sponsor	Silver Sponsor	Bronze Sponsor
Sponsorship Fee	¥800,000	¥600,000	¥400,000	¥200,000
ISSM2022 Invitation (Free)				
Free ticket(s) for ISSM2022	6	4	2	1
ISSM2022 Website				
Company logo placed on ISSM2022 website	Yes	Yes	Yes	Yes
	Upper	Middle	Lower	Lower
Link to corporate website	Yes	Yes	Yes	Yes
ISSM2022 Proceedings				
Recognition of sponsorship in meeting materials along with company logo and link to corporate website	Yes	Yes	Yes	Yes
Company logo printed in color on the brochure on site	Yes	Yes	Yes	Yes
ISSM2022 Screen at site				
Company logo on the screen of interval	Yes	Yes	Yes	Yes
Company logo poster at the Symposium Room	Yes	Yes	Yes	Yes
Table top exhibition				
Provide table and white board to exhibit at the Foyer of the venue	Yes	Yes	Yes	Yes

Note:

- If the event is held online due to an infection situation, the exhibiting format and logo coverage will be changed.
- The deadline to apply for the benefit of having “your logo on the poster” and “table and white board to exhibit” is the end of October.

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